

MRSI Systems, LLC Files Patent Infringement Lawsuit Against Suzhou LieQi in China

MRSI Systems, LLC (a part of Mycronic Group), a global high-tech company that provides high precision production solution in electronics industry, filed a patent infringement lawsuit against Suzhou LieQi Intelligent Equipment Co., Ltd. (SZLQ) with Shenzhen Intermediate People's Court for infringement of MRSI Systems' patent related to die bonder (Case No. (2025) YUE03minchu No. 7154).

The lawsuit seeks damages and a court order to stop SZLQ from making, using, selling, or offering for sale its high precision eutectic mounter infringing on MRSI Systems' patent (Patent No. 201680048482.5), titled "Die Placement Head with Turret".

In 2021, a new legal entity in China - MRSI Automation (Shenzhen) CO., LTD was established, and a new Product Demonstration Center in Shenzhen was launched. As part of long-term commitment to China, MRSI Systems places a strong emphasis on the local R&D, business development, strategic investments and stringent IP protection to foster innovation and customer success in China.

MRSI Systems, LLC 在中国对苏州猎奇提起专利侵权诉讼

Mycronic集团旗下为电子行业提供高精度产品解决方案的全球高科技企业MRSI 系统有限公司（MRSI Systems, LLC），已针对苏州猎奇智能设备股份有限公司（以下简称“苏州猎奇”）向深圳市中级人民法院提起了专利侵权诉讼（案号：（2025）粤 03民初7154号），主张苏州猎奇侵犯了其芯片贴装设备相关的专利。

MRSI 系统有限公司在该诉讼中主张侵权赔偿，并要求法院判令苏州猎奇立即停止制造、使用、销售或许诺销售侵犯其专利（专利号201680048482.5，题为“具有转台的裸片放置头”）的高精度共晶贴片机。

2021年，继MRSI Systems, LLC 在中国深圳设立新的产品演示中心之后，Mycronic集团又在中国注册成立了新的公司 – 迈锐斯自动化(深圳)有限公司。为了长期服务中国市场，公司持续加大在中国本土的研发投入、业务拓展和战略投资，同时通过加强知识产权保护，为国内客户提供创新可靠的解决方案，致力于帮助客户取得商业成功。

About MRSI Systems, LLC

MRSI Systems, LLC is the leading manufacturer of fully automated, high-speed, high-precision and flexible eutectic and epoxy die bonding systems. We leverage over 40 years of industry expertise in high-accuracy die bonders, active aligners, and fluid dispensers to deliver unparalleled precision and reliability for R&D, NPI, and high-volume manufacturing of photonic devices such as lasers, detectors, modulators, WDM/EML TO-Cans, Optical transceivers, LiDAR, VR/AR, sensors, silicon photonics, co-packaging optics, and optical imaging products. We provide the most flexible assembly solutions for all packaging levels including chip-on-wafer (CoW), chip-on-carrier (CoC), PCB, and gold-box packaging. Our commitment to excellence ensures we meet our customers' needs with meticulous attention to detail and 24/7 field support. For more information visit www.mycronic.com/product-areas/die-bonding/.

MRSI Systems, Mycronic Group